

**Features**

- Uses CRM(CQ) advanced SkyMOS3 technology
- Extremely low on-resistance  $R_{DS(on)}$
- Excellent  $Q_g \times R_{DS(on)}$  product(FOM)
- Qualified according to JEDEC criteria

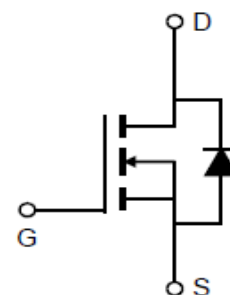
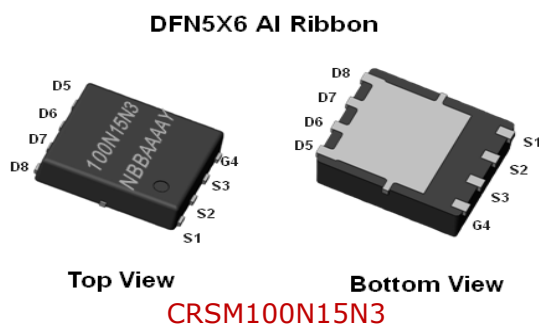
**Applications**

- Synchronous Rectification for AC/DC Quick Charger
- Battery management
- UPS (Uninterruptible Power Supplies)

**Product Summary**

$V_{DS}$	150V
$R_{DS(on)@10V \text{ typ}}$	8.8mΩ
$I_D$	75A

**100% Avalanche Tested**  
**100% DVDS Tested**


**Package Marking and Ordering Information**

Part #	Marking	Package	Packing	Reel Size	Tape Width	Qty
CRSM100N15N3	100N15N3	DFN5*6 Rib	Tape&Reel	N/A	N/A	5000pcs

**Absolute Maximum Ratings**

Parameter	Symbol	Value	Unit
Drain-source voltage	$V_{DS}$	150	V
Continuous drain current $T_C = 25^\circ\text{C}$ (Silicon limit) $T_C = 100^\circ\text{C}$ (Silicon limit)	$I_D$	75 54	A
Pulsed drain current ( $T_C = 25^\circ\text{C}$ , $t_p$ limited by $T_{jmax}$ )	$I_{D \text{ pulse}}$	300	A
Avalanche energy, single pulse ( $I_{as}=30\text{A}$ , $R_g=25\Omega$ )	$E_{AS}$	225	mJ
Gate-Source voltage	$V_{GS}$	$\pm 20$	V
Power dissipation ( $T_C = 25^\circ\text{C}$ )	$P_{tot}$	128	W
Operating junction and storage temperature	$T_j, T_{stg}$	-55...+150	$^\circ\text{C}$
Soldering temperature, wave soldering only allowed at leads (1.6mm from case for 10s)	$T_{sold}$	260	$^\circ\text{C}$

**Thermal Resistance**

Parameter	Symbol	Value			Unit	Test Condition
		min.	typ.	max.		
Thermal resistance, junction – case.	RthJC	-	0.75	1.0	°C/W	-
Thermal resistance, junction - ambient(min. footprint)	RthJA	-	-	60.5	°C/W	-

**Electrical Characteristic (at Tj = 25 °C, unless otherwise specified)**

Parameter	Symbol	Value			Unit	Test Condition
		min.	typ.	max.		

**Static Characteristic**

Drain-source breakdown voltage	$BV_{DSS}$	150	-	-	V	$V_{GS}=0V, I_D=250\mu A$
Gate threshold voltage	$V_{GS(th)}$	2.0	3.0	4.0	V	$V_{DS}=V_{GS}, I_D=250\mu A$
Zero gate voltage drain current	$I_{DSS}$	-	0.1	1	$\mu A$	$V_{DS}=120V, V_{GS}=0V$ $T_j=25^\circ C$
		-	10	100		$T_j=125^\circ C$
Gate-source leakage current	$I_{GSS}$	-	-	100	nA	$V_{GS}=\pm 20V, V_{DS}=0V$
Drain-source on-state resistance	$R_{DS(on)}$	-	8.8	10.0	mΩ	$V_{GS}=10V, I_D=40A$
		-	9.8	11.3		$V_{GS}=8V, I_D=20A$
Transconductance	$g_{fs}$	-	55	-	S	$V_{DS}=5V, I_D=40A$

**Dynamic Characteristic**

Input Capacitance	$C_{iss}$	1470.7	2206	3309	pF	$V_{GS}=0V, V_{DS}=75V,$ $f=1MHz$
Output Capacitance	$C_{oss}$	254.2	381.3	571.95		
Reverse Transfer Capacitance	$C_{rss}$	20	30	60		
Gate Total Charge	$Q_G$	22.7	34	51.0	nC	$V_{GS}=10V, V_{DS}=75V,$ $I_D=40A, f=1MHz$
Gate-Source charge	$Q_{gs}$	9.9	14.9	22.4		
Gate-Drain charge	$Q_{gd}$	4.8	7.2	10.8		
Turn-on delay time	$t_{d(on)}$	7.3	14.6	29.2	ns	$V_{GS}=10V,$ $V_{DD}=75V,$ $I_D=44A, R_{G\_ext}=2.7\Omega$
Rise time	$t_r$	40.3	80.6	161.2		
Turn-off delay time	$t_{d(off)}$	11.15	22.3	44.6		
Fall time	$t_f$	29.35	58.7	117.4		

Gate resistance	$R_G$	1	1.45	2.2	$\Omega$	$V_{GS}=0V, V_{DS}=0V,$ $f=1MHz$
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**Body Diode Characteristic**

Parameter	Symbol	Value			Unit	Test Condition
		min.	typ.	max.		
Body Diode Forward Voltage	$V_{SD}$	0.7	1.00	1.30	V	$V_{GS}=0V, I_{SD}=40A$
Body Diode Continuous Forward Current	$I_S$	-	-	75	A	TC = 25°C
Body Diode Pulsed Current	$I_S$ pulse	-	-	300	A	TC = 25°C
Body Diode Reverse Recovery Time	$t_{rr}$	49.26	73.89	110.835	ns	$I_F=40A, dI/dt=100A/\mu s$
Body Diode Reverse Recovery Charge	$Q_{rr}$	114.67	172	258	nC	

## Typical Performance Characteristics

Fig 1: Output Characteristics

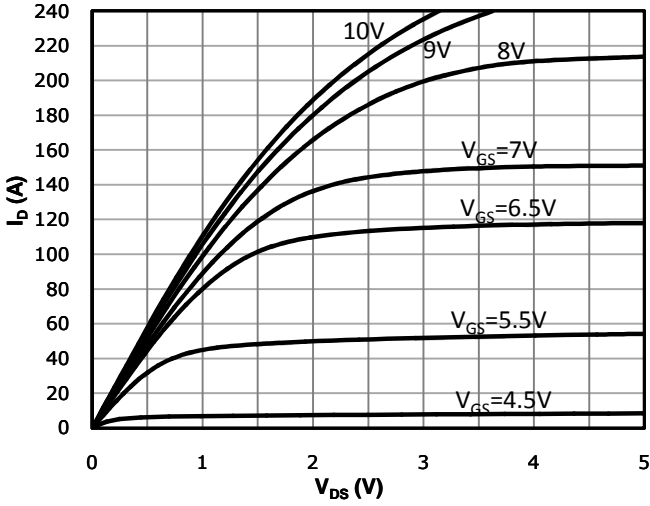


Fig 2: Transfer Characteristics

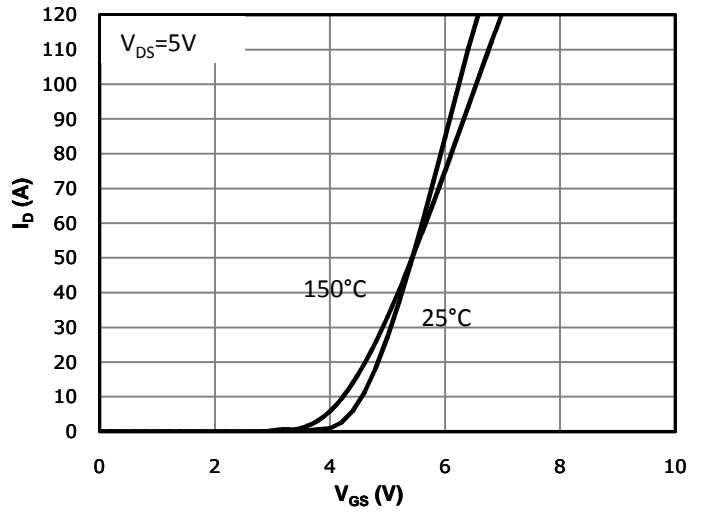


Fig 3:  $R_{DS(on)}$  vs Drain Current and Gate Voltage

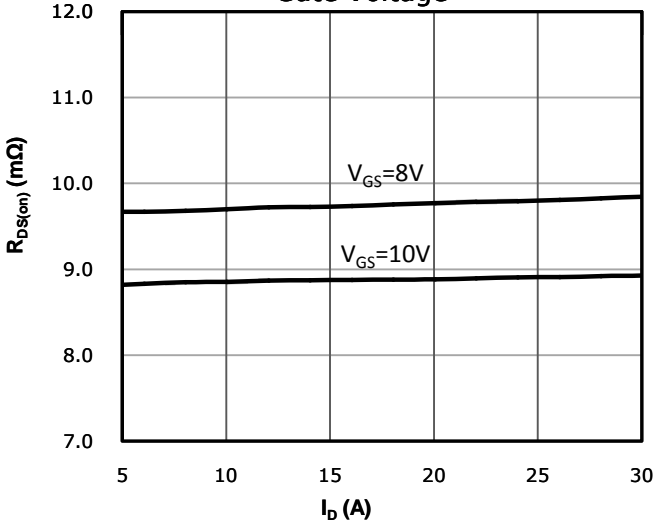


Fig 4:  $R_{DS(on)}$  vs Gate Voltage

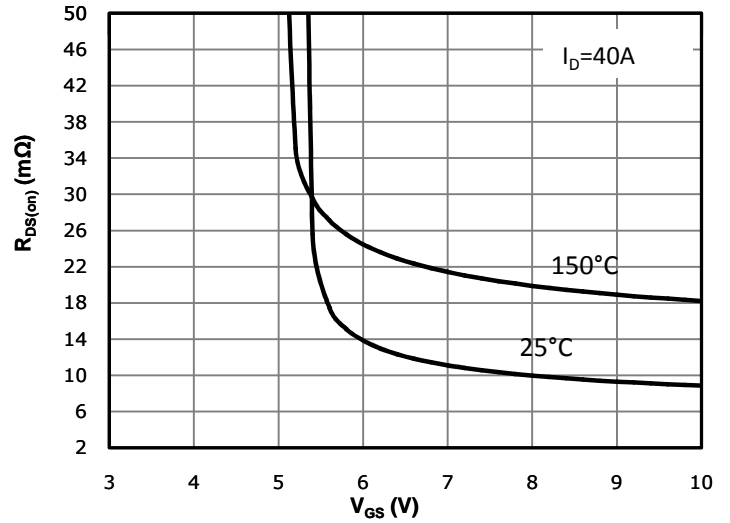


Fig 5:  $R_{DS(on)}$  vs. Temperature

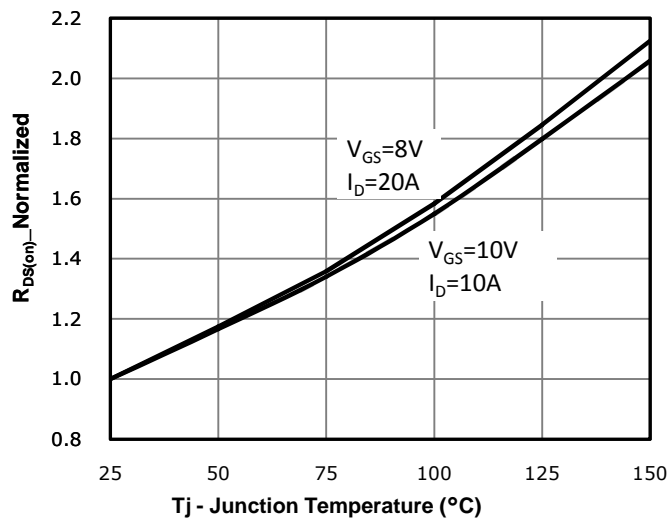


Fig 6: Capacitance Characteristics

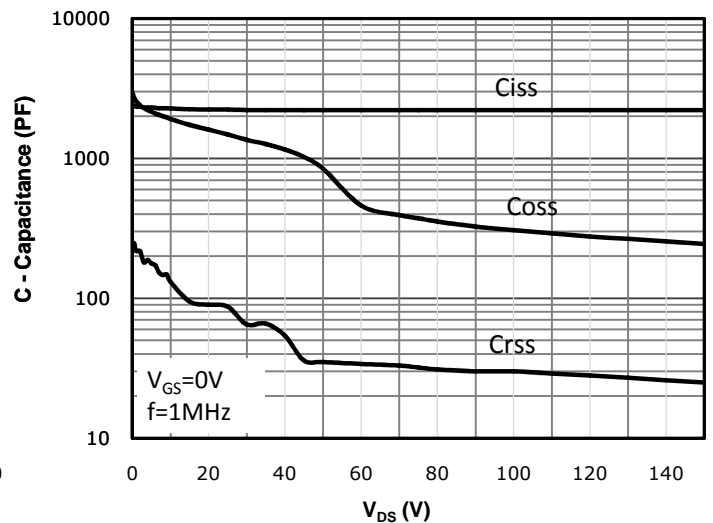


Fig 7: Gate Charge Characteristics

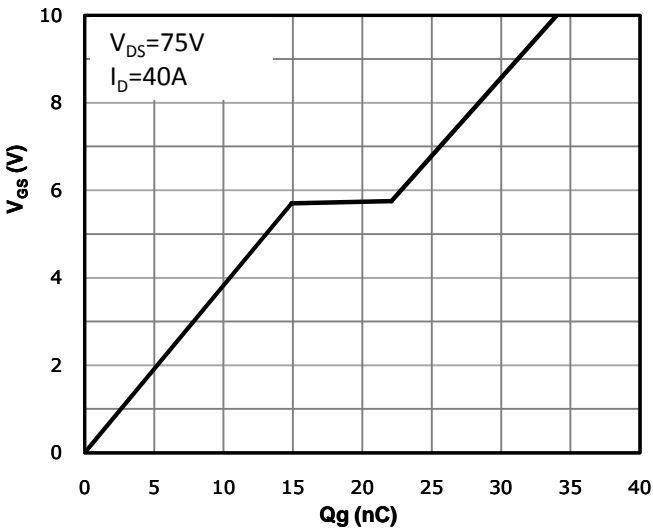


Fig 8: Body-diode Forward Characteristics

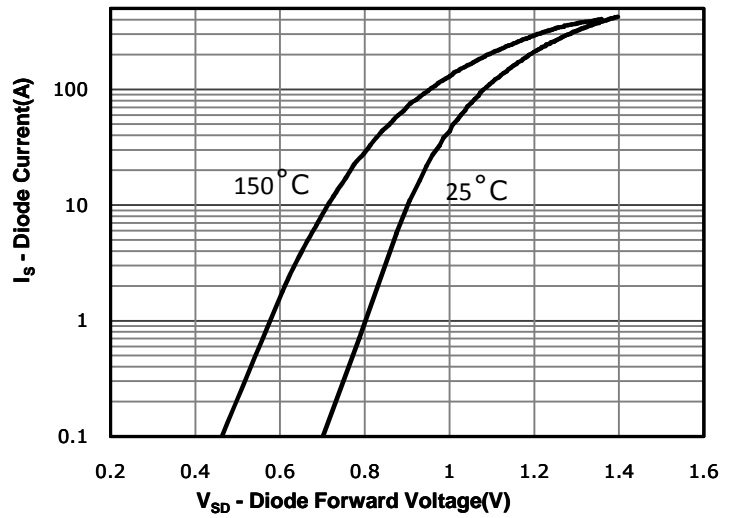


Fig 9: Power Dissipation

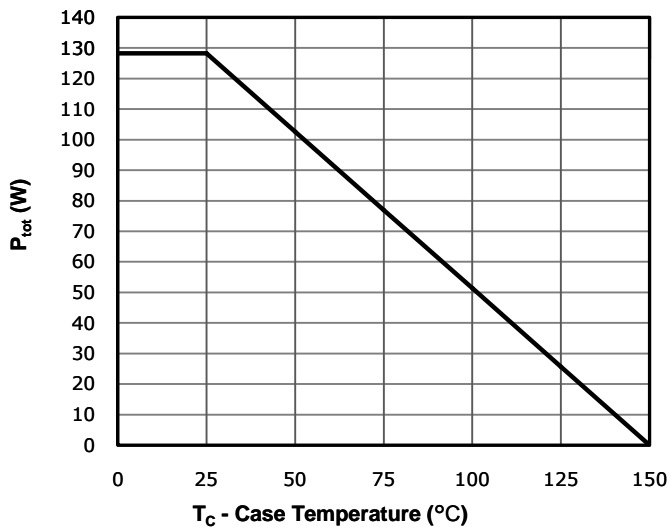


Fig 10: Drain Current Derating

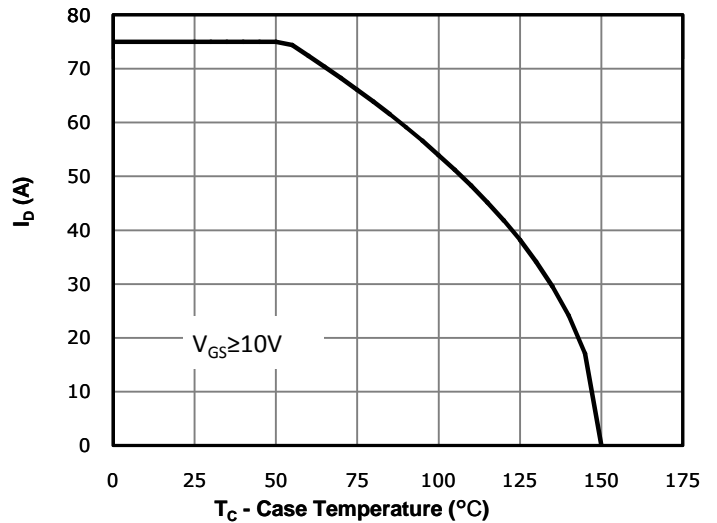


Fig 11: Safe Operating Area

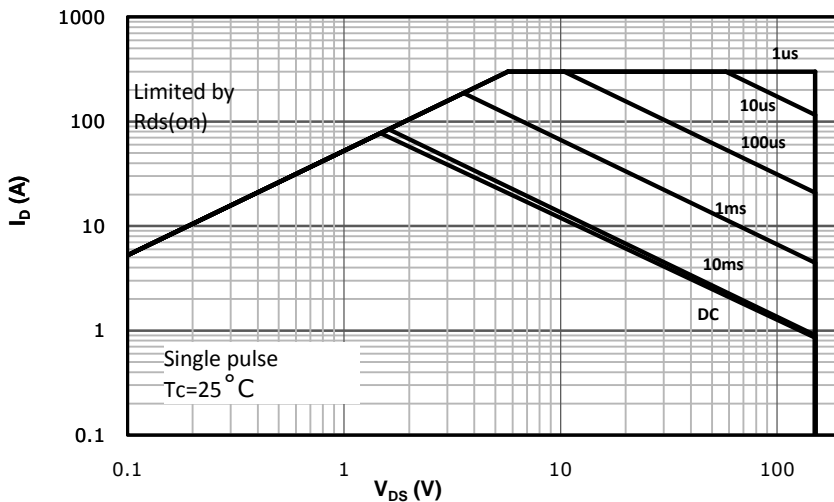
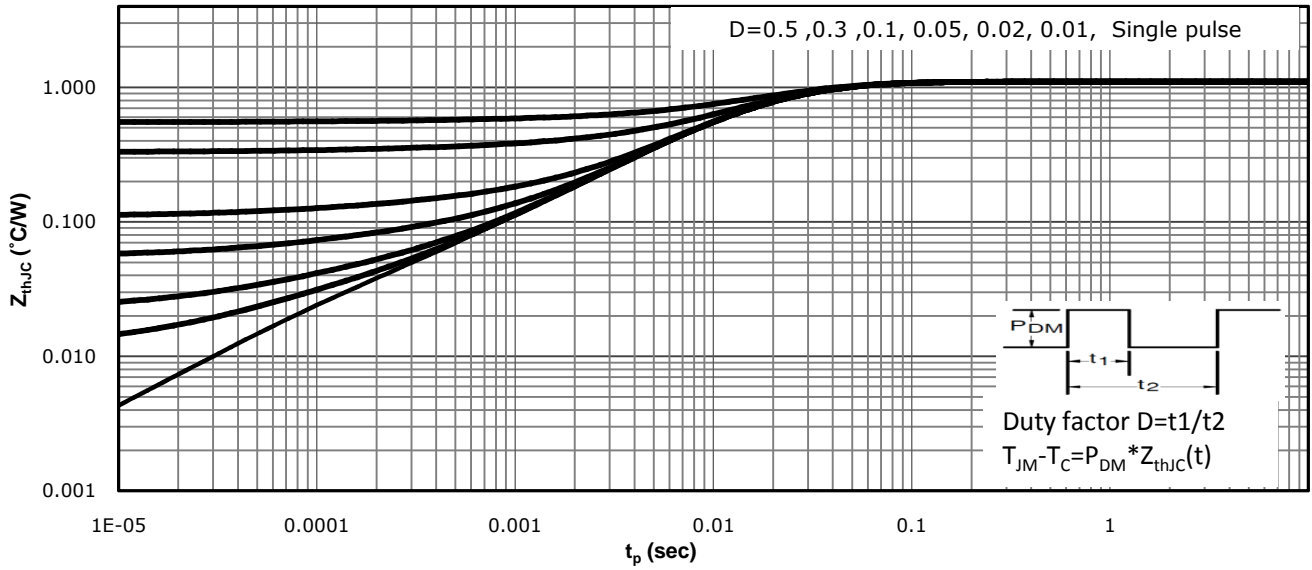
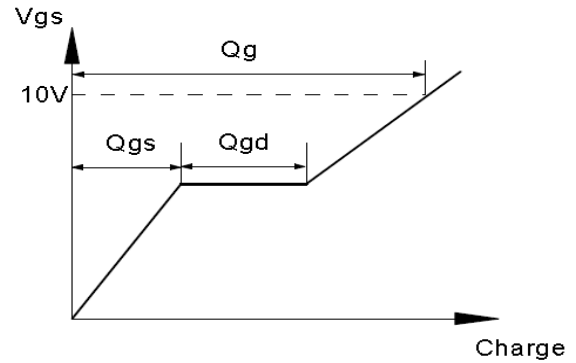
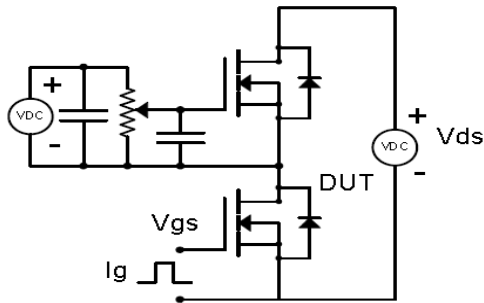


Fig 12: Max. Transient Thermal Impedance

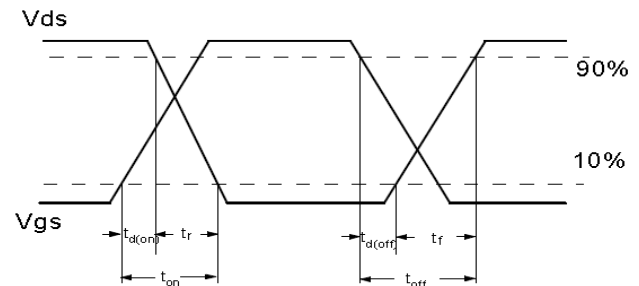
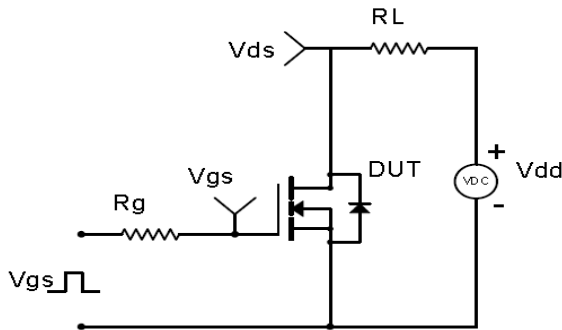


## Test Circuit & Waveform

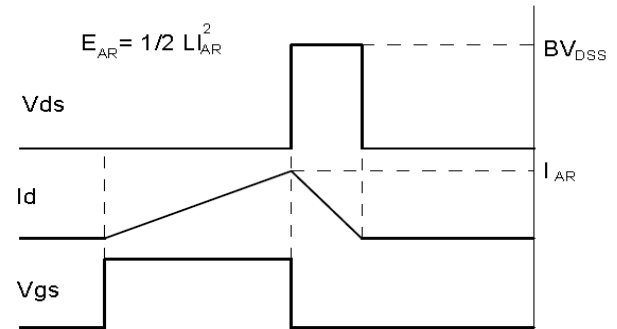
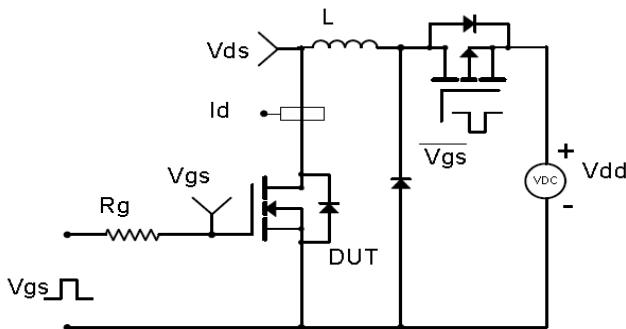
Gate Charge Test Circuit & Waveform



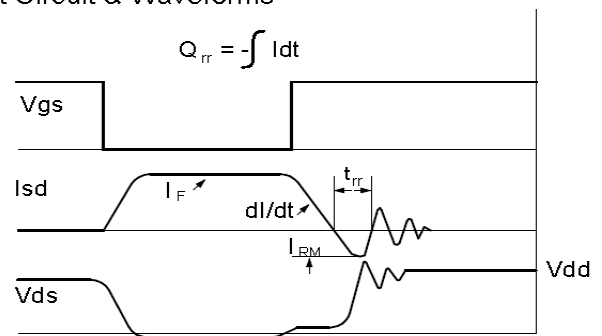
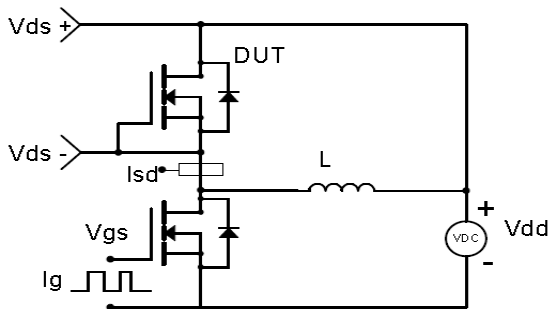
Resistive Switching Test Circuit & Waveforms

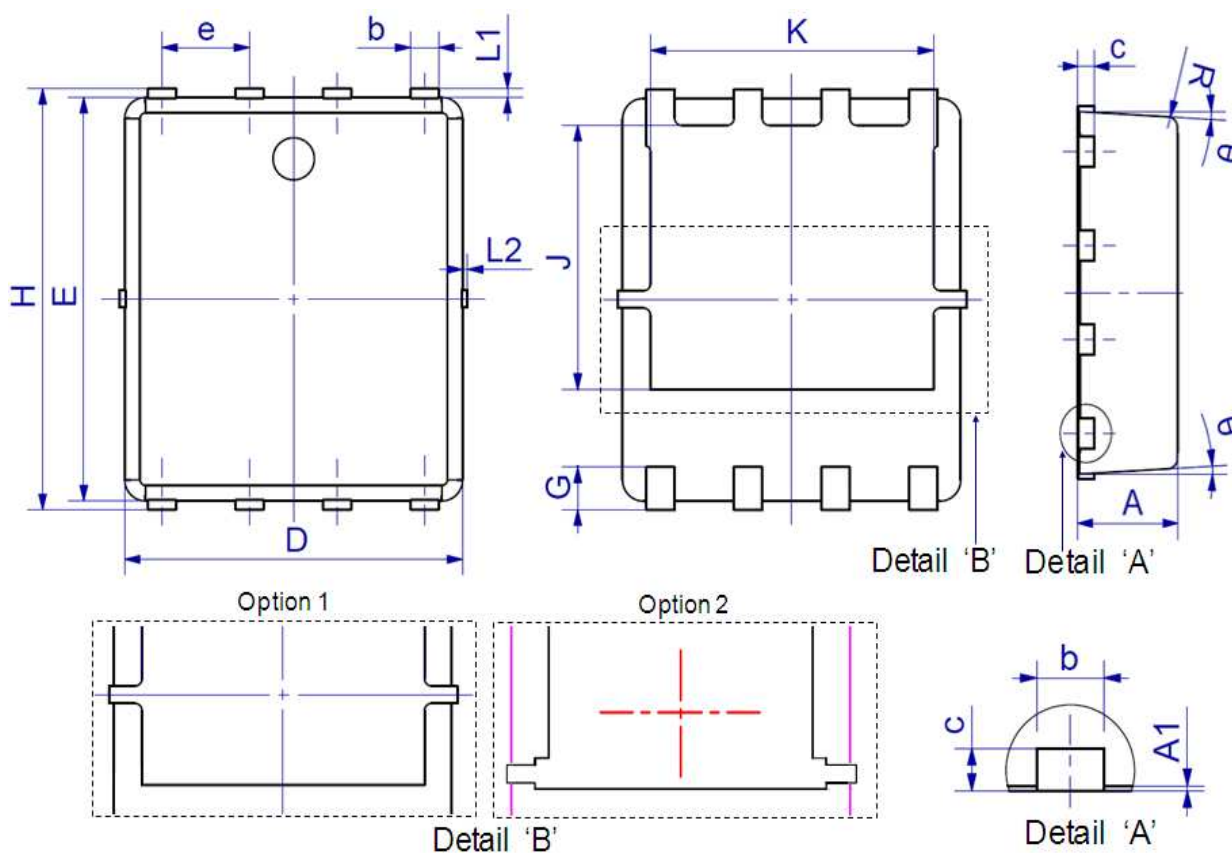


Unclamped Inductive Switching (UIS) Test Circuit & Waveforms



Diode Recovery Test Circuit & Waveforms



**Package Outline: DFN5X6 Cu Clip**


Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	0.80	1.20	0.031	0.047
A1	0.00	0.05	0.000	0.002
b	0.30	0.51	0.012	0.020
c	0.15	0.35	0.006	0.014
D	4.80	5.40	0.189	0.213
e	1.27 BSC		0.050 BSC	
E	5.66	6.06	0.223	0.239
G	0.30	0.71	0.012	0.028
H	5.90	6.35	0.232	0.250
J	3.32	3.92	0.131	0.154
K	3.61	4.25	0.142	0.167
L1	0.05	0.25	0.002	0.010
L2	0.00	0.15	0.000	0.006
R	0.25 REF		0.010 REF	
θ	0°	12°	0°	12°



## Marking



NOTE:

NXBBAAAAY

N	—Wire Bond code
X	—Assembly location code
BB	—Fab code
AAAA	—Lot code
Y	—Bin code

**Revision History**

Revision	Date	Major changes
1.0	2020-6-30	Release of Preliminary Version.
2.0	2020-9-15	Supplement Dynamic Upper/Lower Limit

**Disclaimer**

Unless otherwise specified in the datasheet, the product is designed and qualified as a standard commercial product and is not intended for use in applications that require extraordinary levels of quality and reliability, such as automotive, aviation/aerospace and life-support devices or systems.

Any and all semiconductor products have certain probability to fail or malfunction, which may result in personal injury, death or property damage. Customer are solely responsible for providing adequate safe measures when design their systems.

CRM(CQ) reserves the right to improve product design, function and reliability without notice.